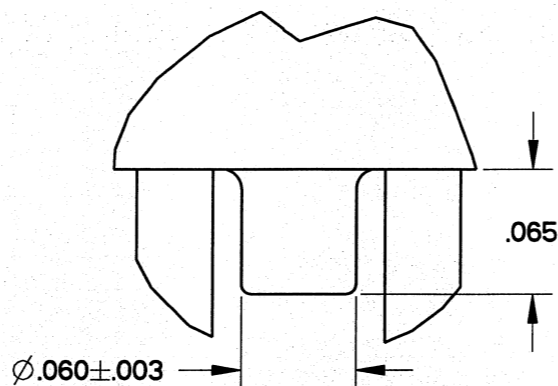
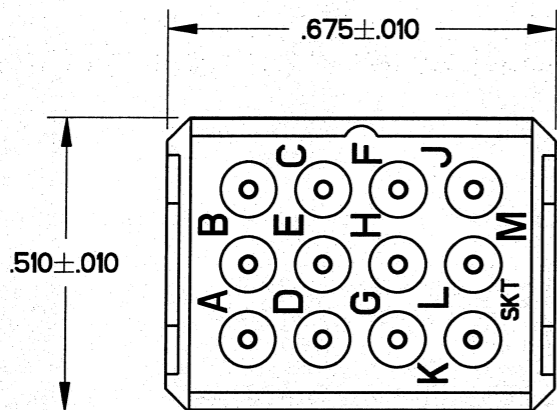
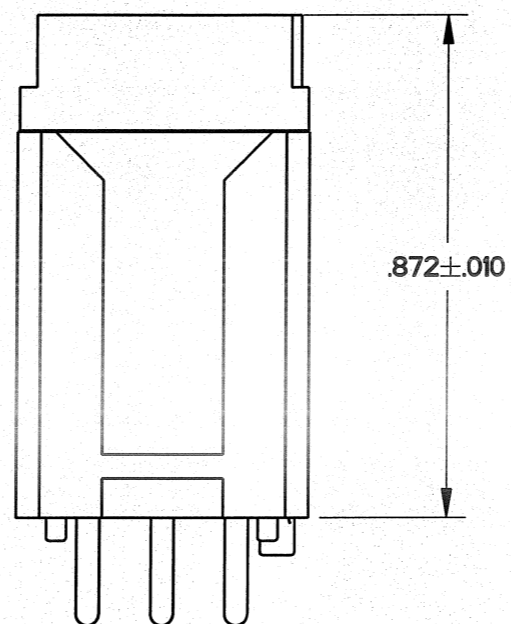
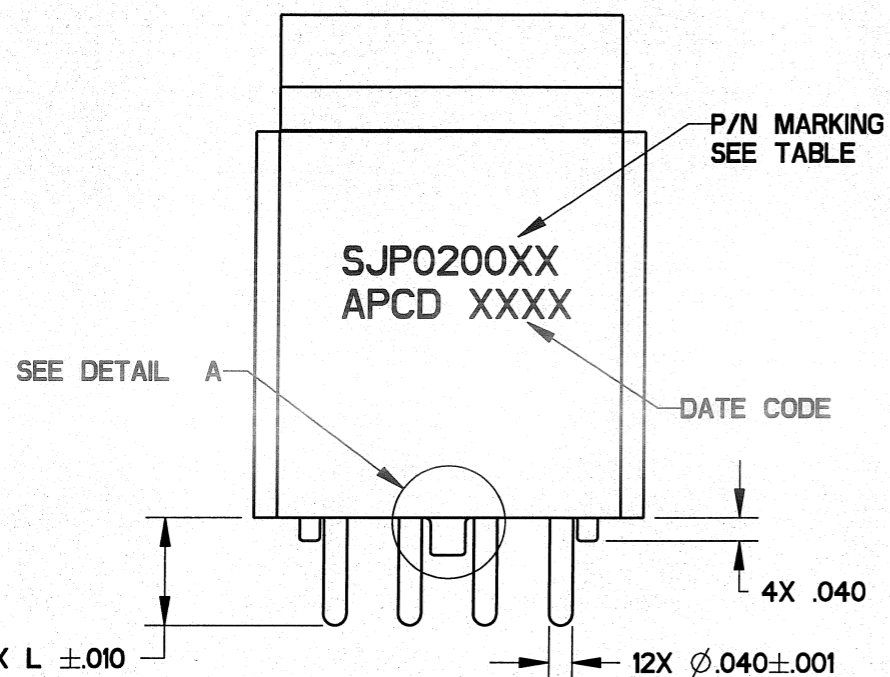
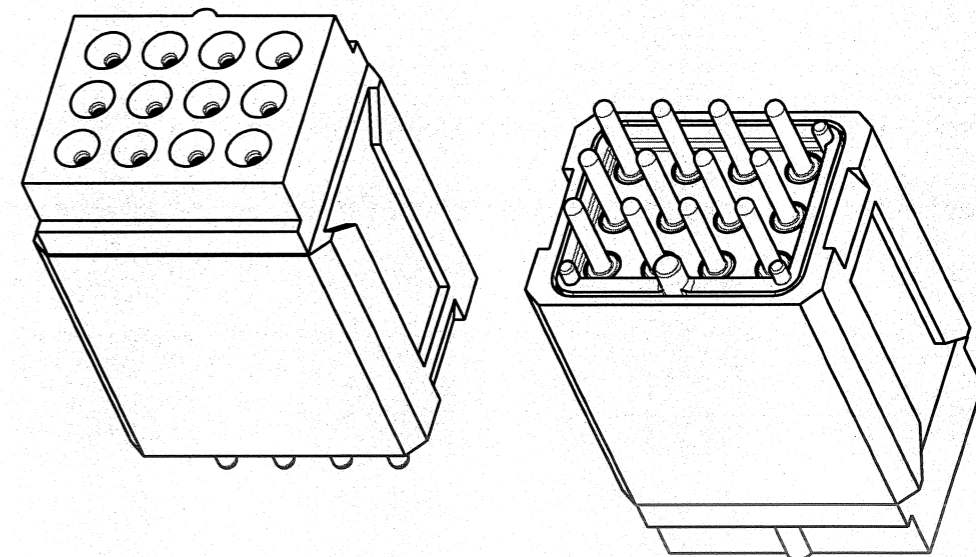


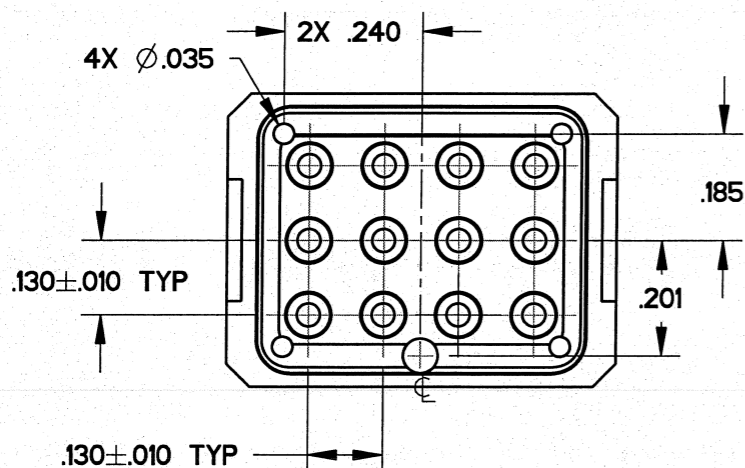
REV	ECN	APP'D
-	5873	JT 7/31/06
A	6062	JT 4/27/07
B	6070	JT 5-21-07
C	6166	JT 12/26/07
D	6167	JT 1/4/08
E	6221	JT 5/23/08
F	6246	JT 8/11/08



DETAIL A  
SCALE 10:1



- NOTES:
- MATERIALS:  
 BODY: POLYETHERIMIDE PER MIL-P-46184, VIRGIN MATERIAL ONLY.  
 GROMMET: SILICONE BLEND ELASTOMER.  
 CONTACT RETAINERS: STAINLESS STEEL.  
 INTERNAL/EXTERNAL PIN CONTACTS: COPPER ALLOY, HARD GOLD PLATE PER MIL-DTL-45204.
  - MODULE ACCEPTS M39029/22-192 CONTACT AND MS27488-20 SEALING PLUG.
  - INSULATION RESISTANCE: 5000 MEGAOHMS MIN AT 25°C



PART NO.	CONTACTS SUPPLIED	LENGTH "L"	P/N MARKING
SJP020000	M39029/22-192, QTY 13	.187	SJP020000
SJP020001	NONE		
SJP020010	M39029/22-192, QTY 13	.250	SJP020010
SJP020011	NONE		

DIMENSIONS	TOLERANCES	PROJECTION	TITLE		
ANSI Y14.5M UNITS: INCHES Pro/E FILE	.XX ±0.01 .XXX ±0.005 ANGLES ±2.0°		SOCKET MODULE, SJP PC MOUNT SIZE 20		
ORIGINAL	THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION WHICH IS THE CONFIDENTIAL PROPERTY OF AMPHENOL PCD, BEVERLY, MA	ENGR <i>R. Swaine</i> APPD <i>J. Swaine</i>	DRWN R. SWAINE 7/28/06	SIZE B	DWG NO. SJP020000_C
				REV F	
			CODE: 58982	SCALE: 2:1	SHEET 1 OF 1

SJP020000\_C

SJP020000\_C